

Features

- 1008 size
- Available in E12 series
- High Q
- High operating temperature of 125 °C
- RoHS compliant*

Applications

- Mobile phones
- Cellular phones
- CTV, VCR, HIC, FDD

CW252016 Series - High Q Chip Inductors

Electrical Specifications

Bourns® Part No.	Inductance		Q	Test Freq. (MHz)		SRF (MHz)	RDC (Ohms)		I _{rms} (mA)
	nH	Tol. %		Min.	L		Q	Min.	
CW252016-10NK	10	±10	50	100	500	4100	0.08	600	
CW252016-12NK	12	±10	50	100	500	3300	0.09	600	
CW252016-15NK	15	±10	40	100	350	2500	0.10	500	
CW252016-18NK	18	±10	50	100	350	2500	0.11	600	
CW252016-22NK	22	±10	55	100	350	2400	0.12	600	
CW252016-27NK	27	±10	55	100	350	1600	0.13	600	
CW252016-33NK	33	±10	60	100	350	1600	0.14	600	
CW252016-39NK	39	±10	60	100	350	1500	0.15	600	
CW252016-47NK	47	±10	60	100	350	1500	0.16	600	
CW252016-56NJ	56	±5	60	100	350	1300	0.18	600	
CW252016-68NJ	68	±5	60	100	350	1300	0.20	600	
CW252016-82NJ	82	±5	60	100	350	1000	0.22	600	
CW252016-R10J	100	±5	60	100	350	1000	0.56	500	
CW252016-R12J	120	±5	50	25	100	950	0.63	500	
CW252016-R15J	150	±5	45	25	100	850	0.70	500	
CW252016-R18J	180	±5	45	25	100	750	0.77	500	
CW252016-R22J	220	±5	45	25	100	700	0.84	500	
CW252016-R27J	270	±5	45	25	100	600	0.91	500	
CW252016-R33J	330	±5	45	25	100	570	1.05	500	
CW252016-R39J	390	±5	45	25	100	500	1.12	400	
CW252016-R47J	470	±5	45	25	100	450	1.19	470	
CW252016-R56J	560	±5	45	25	100	415	1.33	400	
CW252016-R68J	680	±5	45	25	100	375	1.55	400	
CW252016-R82J	820	±5	45	25	100	350	2.30	360	
CW252016-1R0J	1000	±5	25	25	50	290	1.75	330	
CW252016-1R2J	1200	±5	25	7.9	7.9	250	2.00	280	
CW252016-1R5J	1500	±5	25	7.9	7.9	200	2.30	280	
CW252016-1R8J	1800	±5	25	7.9	7.9	160	2.60	270	
CW252016-2R2J	2200	±5	25	7.9	7.9	160	2.80	250	
CW252016-2R7J	2700	±5	22	7.9	7.9	70	3.20	195	
CW252016-3R3J	3300	±5	22	7.9	7.9	55	3.40	185	
CW252016-3R9J	3900	±5	20	7.9	7.9	48	3.60	180	
CW252016-4R7J	4700	±5	18	7.9	7.9	43	4.00	175	

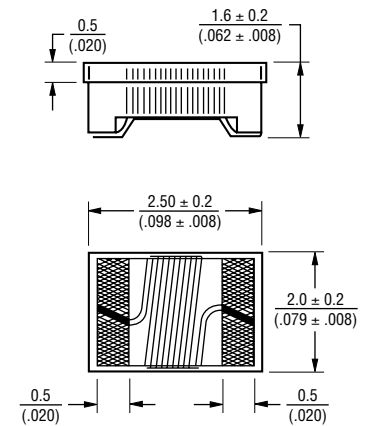
General Specifications

Temperature Rise40 °C max. at rated current
 Operating Temperature-40 °C to +125 °C
 Storage Temperature-40 °C to +125 °C
 Reflow Soldering .. 230 °C, 50 sec. max.
 Resistance to Soldering Heat +260 °C, 5 seconds

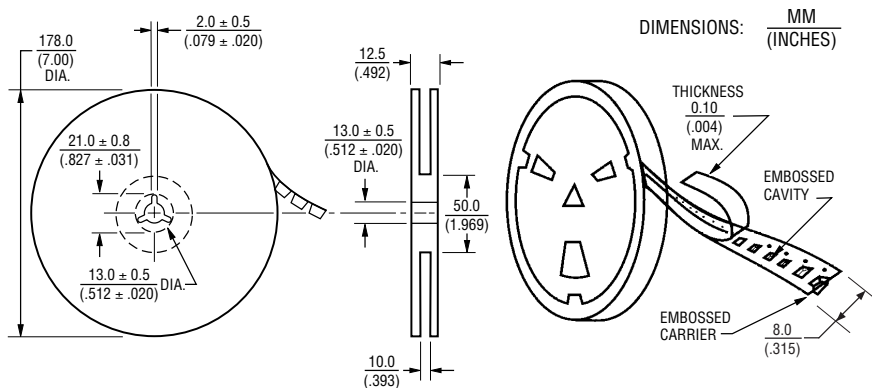
Materials

Core Material
 -10NK thru -R82JCeramic
 -1R0J thru -4R7JFerrite
 Wire Enameled copper (1W1E180)
 Terminal Mo/Mn+Ni+Au
 Packaging 2,000 pcs. per reel

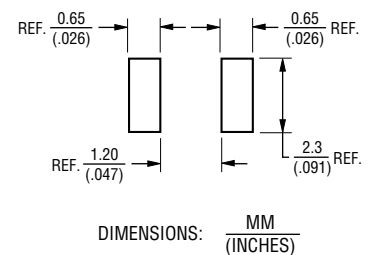
Product Dimensions



Packaging Specifications



Recommended Layout



REV. 08/16

*RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.